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CEO

Femtoflash, the New Femtosecond GHz-burst Laser for Industrial Micromachining

9 January 2024. 16:00 - 17:00 CET

EPIC Members
New Product Release



Company

Lithium Lasers is an innovative startup focused on the development and the usage of innovative ultra short pulse laser (USPL) technologies

- Founded in 2019
- Spinoff of Politecnico di Milano
- Operational headquarter with laboratories in Polo Meccatronica, Rovereto (TN)



TRENTINOSVILUPPO
IMPRESA INNOVAZIONE MARKETING TERRITORIALE

Lithium Six

Scientific USP laser



High power femtosecond laser

80 MHz
150 fs
1050 and 525 nm
up to 7 W

FEMTOFLASH

Micromachining USP laser



Femtosecond GHz burst laser

800 MHz
400 fs
1030 and 515 nm
up to 50 W
flexible burst mode

Application Support

Micro-processing Workshop



Your trusted partner in micromachining

Thanks to our expertise in laser technology we offer:

- feasibility studies
- proof-of-concept experiments

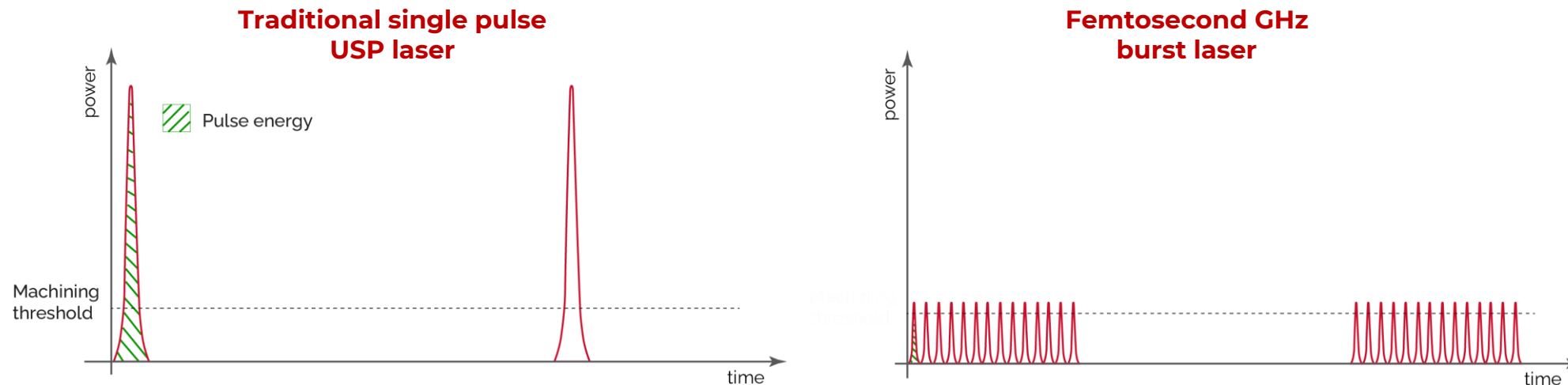
Background - Precision meets speed in the GHz era

Traditional single pulse USP lasers: individual high-energy pulses at repetition rates up to 10 MHz.

- **Tradeoff speed and precision:** slow machining speed to avoid that surplus energy causes detrimental effects compromising machining quality.

Femtosecond GHz burst laser: bursts of high-frequency pulses.

- **Higher machining speed:** the energy is distributed over many pulses that are clustered in bursts and the pulse frequency is increased a thousandfold (GHz level)
- **Higher machining quality:** strategic energy management with energy of each pulse within the burst just above the machining threshold (few μJ)



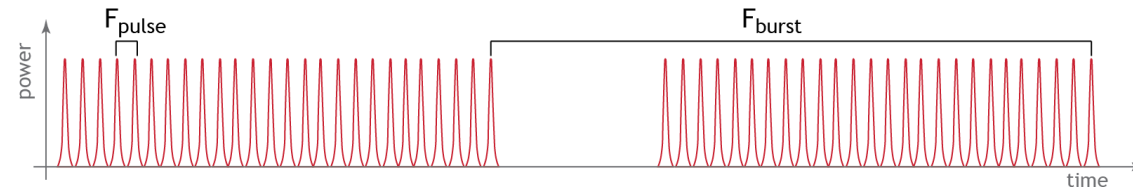


KEY FEATURES AND BENEFITS:

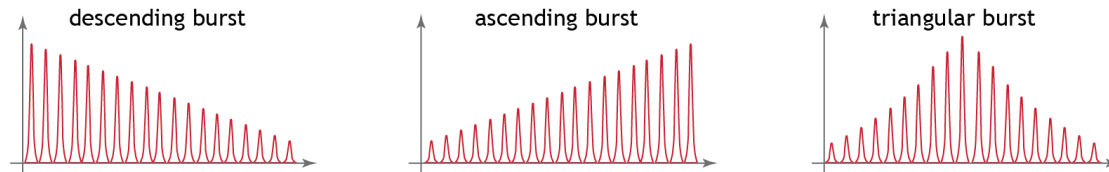
- Bursts of high frequency femtosecond pulses
- New highly efficient machining regime
- Flexible n. of pulses in the bursts (from 25 up to more than 1000)
- Tailorable energy distribution onto the workpiece
- Compact and lightweight industrial design

SPECIFICATIONS:

Center wavelength	1032 nm
Pulse duration	< 400 fs
Average power	Up to 50 W
RMS power noise	0.12 %
Inter-burst frequency (F_{burst})	Up to 10 MHz
Intra-burst frequency (F_{pulse})	0.8 GHz
Beam quality	$M2 < 1.2$
Beam ellipticity	1.01
Warm-up time	< 10 min
Operational temperature	15 - 35 °C
Tot power consumption	450 W
Laser dimensions	420 X 294 X 159 mm
Laser weight	16 kg



Flexible burst shapes:



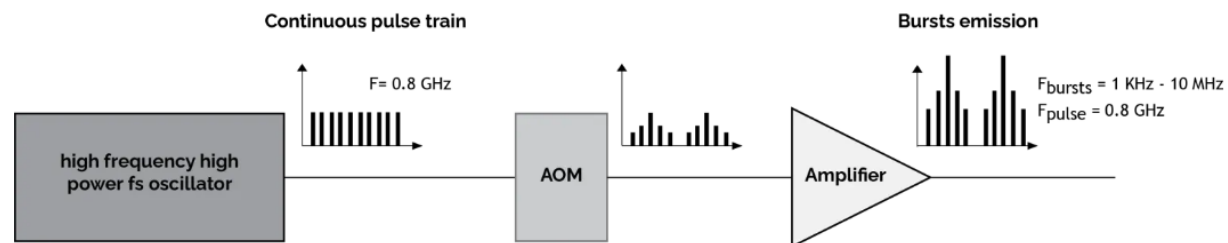
Proprietary rugged industrial design

NO CPA - ONLY 3 MODULES DESIGN

Traditional USP lasers for material processing that have a complex structure of at least 7 modules based on Chirped Pulse Amplification (CPA) and multistage amplifiers.

FEMTOFLASH boasts a sleek industrial design consisting of just 3 modules:

1. high power soliton mode-locked seed oscillator
2. acousto-optic modulator (AOM)
3. only one high-gain single-stage amplifier



EASY TO HANDLE AND INSTALL

- one single enclosure with control electronics integrated
- weight of only 16 Kg
- dimension of 20 X 294 X 159 mm,
- power consumption of less than 500 W



Single pulse USP laser vs FEMTOFLASH

Material processed: stainless still

Processing: 10 passes milling at 0.1 m/s with a beam spot diameter of 10 μm

Lasers:

- commercially available USP laser: 50 W, 1064 nm, 10 ps, single pulse mode
- FEMTOFLASH: 20 W, 1030 nm, 400 fs, burst mode

Laser parameters: same average power and rep. rate to compare ablation efficiency

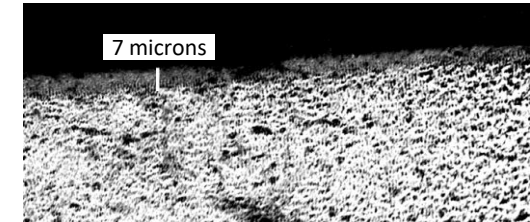
Ablated depth:

- single pulse USP laser: ~ 7 μm
- FEMTOFLASH: ~ 40 μm

Single Pulse USP laser



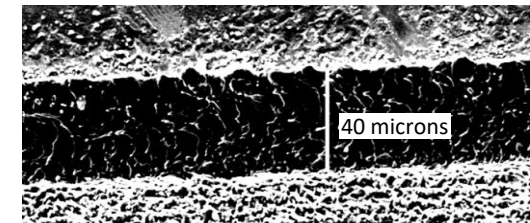
$E_{\text{pulse}} = 100 \mu\text{J}$
Average Power: 2 W
Rep. Rate: 20 KHz



FEMTOFLASH



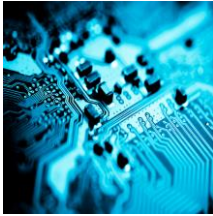
$E_{\text{burst}} = 100 \mu\text{J}$
Average Power: 2 W
Rep. Rate: 20 KHz



	Single Pulse USP laser	FEMTOFLASH	Improvement factor
Ablation efficiency (mm³/Watt/min)	0,15	0,84	x 6
Laser footprint (m³)	0,05	0,02	x 2,5
Laser weight (Kg)	131	31	x 4
Energy consumption (Watt)	2400	460	x 5

Applications – industrial manufacturing

ELECTRONICS



PROCESSES:

- cutting
- drilling
- milling
- soldering

MATERIALS:

- semiconductors
- ceramics
- metals

FOR:

- PCB
- wafer dicing
- wire bonding

MEDICAL



PROCESSES:

- cutting
- drilling
- milling

MATERIALS:

- polymers
- nitinol
- glass

FOR:

- medical devices
- microfluidics
- pharmaceuticals

AERONAUTICS



PROCESSES:

- cutting
- drilling
- milling
- cleaning

MATERIALS:

- metals
- composites

FOR:

- drones
- airplanes

SPACE



PROCESSES:

- cutting
- drilling
- milling
- marking

MATERIALS:

- composites
- metals

FOR:

- satellites
- spacecraft
- space launch systems

LUXURY



PROCESSES:

- cutting
- drilling
- milling
- marking

MATERIALS:

- metals

FOR:

- watches
- jewellery
- glasses

AUTOMOTIVE



PROCESSES:

- cutting
- milling
- marking
- surface structuring

MATERIALS:

- metals
- alloys

FOR:

- pistons and engines
- lighting
- design

Case Study: sub-micron hole drilling on polyimide

SMOOLER PROJECT

Sub-micron holes drilling by flexible burst mode fs laser for nanoparticle analysis



Manufacturing of sub-micron hole on polyimide sheet for the production of flow cells used for nanoparticle analysis

PRODUCT:

Flow cell is a disposable containing a sub-micron hole used in the field of nanoparticle analysis. Applications: viral and bacterial detection, food and water analysis and air pollution analysis.

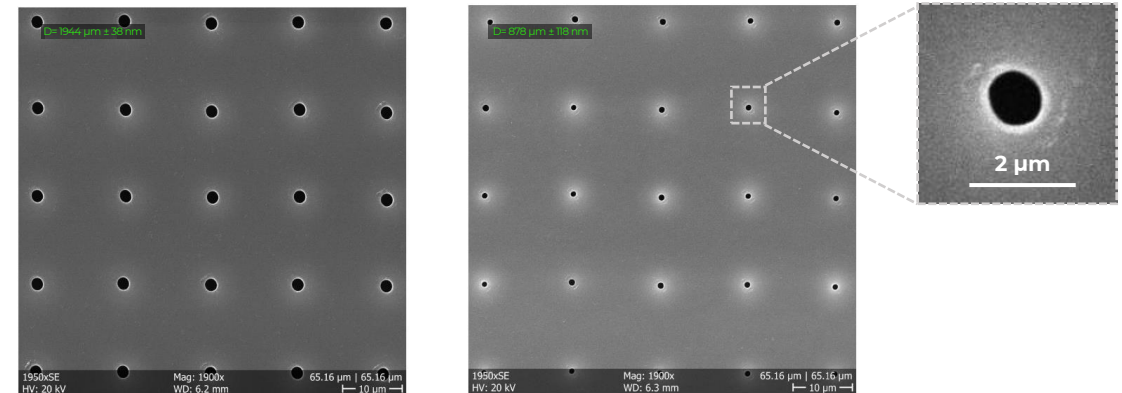
RESULTS:

- **Minimal HAZ**
- Hole diameter decreased up to **less than 1 μm**
- **Perfectly rounded holes**
- **High reproducibility process:**
Mean diameter ± SD = 933 ± 82 nm
(4 films obtained from different batches with 25 holes each for a total of 100 holes)

Type of laser used: FEMTOFLASH Green (515 nm)

CHALLENGES:

- To high hole-hole diameter variability
- Frequent absence of drilling
- None control on hole geometry
- It cannot sustain large scale production



Thank you



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